

BUK768R3-60E

N-channel TrenchMOS standard level FET

13 July 2012

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel MOSFET in a SOT404 package using TrenchMOS technology. This product has been designed and qualified to AEC Q101 standard for use in high performance automotive applications.

1.2 Features and benefits

- AEC Q101 compliant
- Repetitive avalanche rated
- Suitable for thermally demanding environments due to 175 °C rating
- True standard level gate with VGS(th) rating of greater than 1V at 175 °C

1.3 Applications

- 12 V Automotive systems
- Motors, lamps and solenoid control
- Start-Stop micro-hybrid applications
- Transmission control
- Ultra high performance power switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C		-	-	60	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 1</u>	[1]	-	-	75	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 2</u>		-	-	137	W
Static characte	eristics						,
R _{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11		-	5.9	8.3	mΩ
Dynamic characteristics							
Q_{GD}	gate-drain charge	$I_D = 20 \text{ A}$; $V_{DS} = 48 \text{ V}$; $V_{GS} = 10 \text{ V}$; Fig. 14		-	14.6	-	nC

[1] Continuous current is limited by package.



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	mb	D I
2	D	drain		
3	S	source		G
mb	D	mounting base; connected to drain	1 3	mbb076 S
			D2PAK (SOT404)	

3. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
BUK768R3-60E	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404			

4. Limiting values

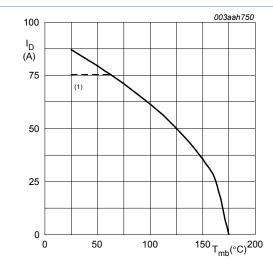
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C		-	60	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20 \text{ k}\Omega$		-	60	V
V_{GS}	gate-source voltage	T _j = 25 °C		-20	20	V
I _D	drain current	T _{mb} = 25 °C; V _{GS} = 10 V; <u>Fig. 1</u>	[1]	-	75	Α
		T _{mb} = 100 °C; V _{GS} = 10 V; <u>Fig. 1</u>		-	61.5	Α
I _{DM}	peak drain current	T_{mb} = 25 °C; pulsed; $t_p \le 10 \mu s$; Fig. 4		-	349	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 2</u>		-	137	W
T _{stg}	storage temperature			-55	175	°C
T _j	junction temperature			-55	175	°C
Source-drain	diode					
Is	source current	T _{mb} = 25 °C	[1]	-	75	Α
I _{SM}	peak source current	pulsed; $t_p \le 10 \ \mu s$; $T_{mb} = 25 \ ^{\circ}C$		-	349	Α

Symbol	Parameter	Conditions		Min	Max	Unit
Avalanche rug	gedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I_D = 75 A; $V_{sup} \le$ 60 V; R_{GS} = 50 Ω; V_{GS} = 60 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 3	[2][3]	-	86	mJ

- [1]
- Continuous current is limited by package. Single-pulse avalanche rating limited by maximum junction temperature of 175 $^{\circ}\text{C}.$
- Refer to application note AN10273 for further information.



(1) Capped at 75A due to package

Continuous drain current as a function of mounting base temperature

$$V_{GS} \ge 10V$$

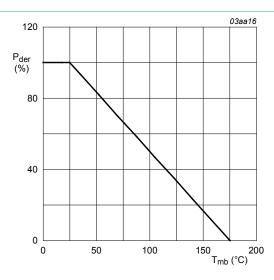
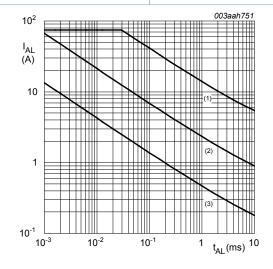


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$



Single pulse avalanche rating; avalanche current as a function of avalanche time

(1)
$$T_{j (int)} = 25^{\circ}C$$
; (2) $T_{j (int)} = 150^{\circ}C$; (3) Repetitive Avalanche

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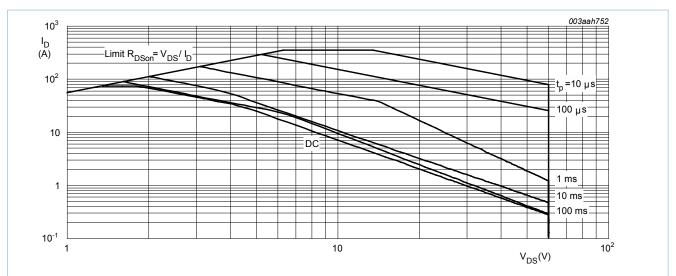


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

 $T_{mb} = 25^{\circ}C$; I_{DM} is a single pulse

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 5	-	-	1.09	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	minimum footprint; mounted on a printed-circuit board	-	50	-	K/W

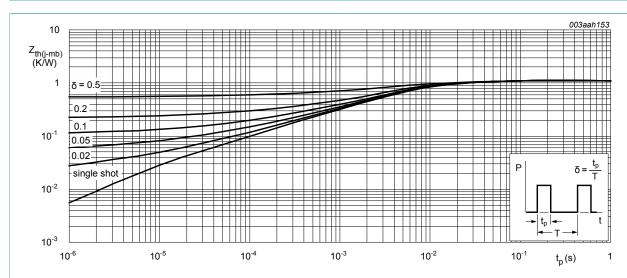


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V _{(BR)DSS}	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 °C$	60	-	-	V
	breakdown voltage	$I_D = 250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = -55 \ ^{\circ}C$	54	-	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 25 °C; Fig. 9; Fig. 10	2.4	3	4	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ °C};$ Fig. 9	1	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C};$ Fig. 9	-	-	4.5	V
I _{DSS}	drain leakage current	V _{DS} = 60 V; V _{GS} = 0 V; T _j = 25 °C	-	0.04	1	μA
		V _{DS} = 60 V; V _{GS} = 0 V; T _j = 175 °C	-	-	500	μA
I _{GSS} gate leakage cur	gate leakage current	V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-	2	100	nA
		V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C	-	2	100	nA
200	drain-source on-state resistance	V_{GS} = 10 V; I_D = 20 A; T_j = 25 °C; Fig. 11	-	5.9	8.3	mΩ
		V _{GS} = 10 V; I _D = 20 A; T _j = 175 °C; Fig. 11; Fig. 12	-	-	18	mΩ
Dynamic c	characteristics					
$Q_{G(tot)}$	total gate charge	I _D = 20 A; V _{DS} = 48 V; V _{GS} = 10 V; Fig. 13; Fig. 14	-	43.1	-	nC
Q _{GS}	gate-source charge	I _D = 20 A; V _{DS} = 48 V; V _{GS} = 10 V;	-	10.9	-	nC
Q_{GD}	gate-drain charge	Fig. 14	-	14.6	-	nC
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz;	-	2188	2920	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 15</u>	-	319	383	pF
C _{rss}	reverse transfer capacitance		-	205	281	pF
t _{d(on)}	turn-on delay time	V_{DS} = 45 V; R_L = 2 Ω ; V_{GS} = 10 V;	-	14	-	ns
t _r	rise time	$R_{G(ext)} = 5 \Omega$	-	27	-	ns
t _{d(off)}	turn-off delay time		-	27	-	ns
t _f	fall time		-	27	-	ns
L _D	internal drain inductance	from upper edge of mounting base to centre of die	-	2.5	-	nH
L _S	internal source inductance	measured from source lead to source bond pad	-	7.5	-	nH

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Source-drain	diode					
V_{SD}	source-drain voltage	$I_S = 20 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 16$	-	0.84	1.2	V
t _{rr}	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	27	-	ns
Q _r	recovered charge	V _{DS} = 25 V	-	24	-	nC

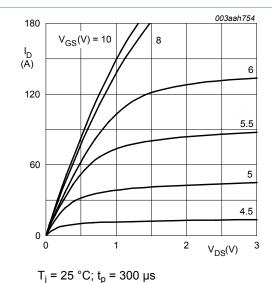


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

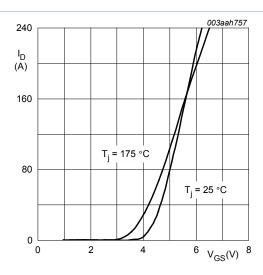


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values



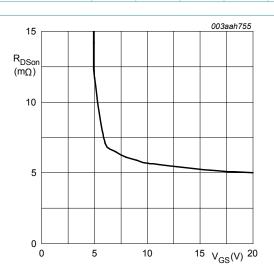


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$$T_j = 20 \,^{\circ}C; I_D = 20A$$

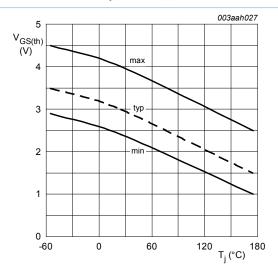


Fig. 9. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1 \text{ mA}; \ V_{DS} = V_{GS}$$

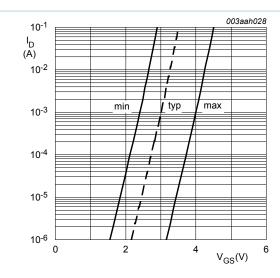


Fig. 10. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25$$
°C; $V_{DS} = 5V$

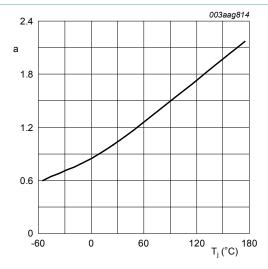
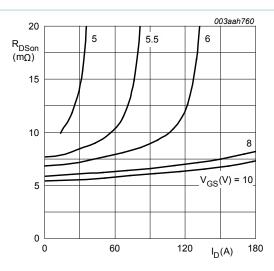


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

$$\mathbf{a} = \frac{R_{DSon}}{R_{DSon(25 \, \text{C})}}$$



$$T_j = 25 \, ^{\circ}C; t_p = 300 \, \mu s$$

Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

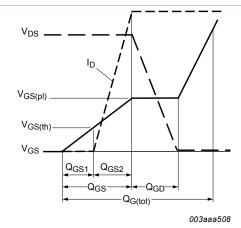


Fig. 13. Gate charge waveform definitions

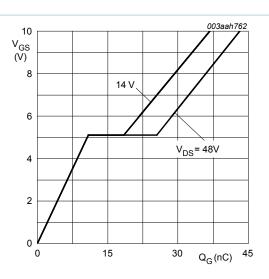


Fig. 14. Gate-source voltage as a function of gate charge; typical values

$$T_j = 25^{\circ}C; I_D = 20A$$

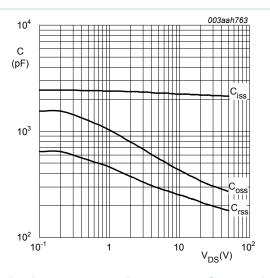


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$$V_{GS} = \mathbf{0}V; f = \mathbf{1}MHz$$

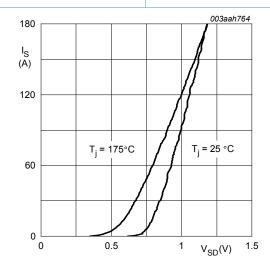


Fig. 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

$$V_{GS} = 0V$$

7. Package outline

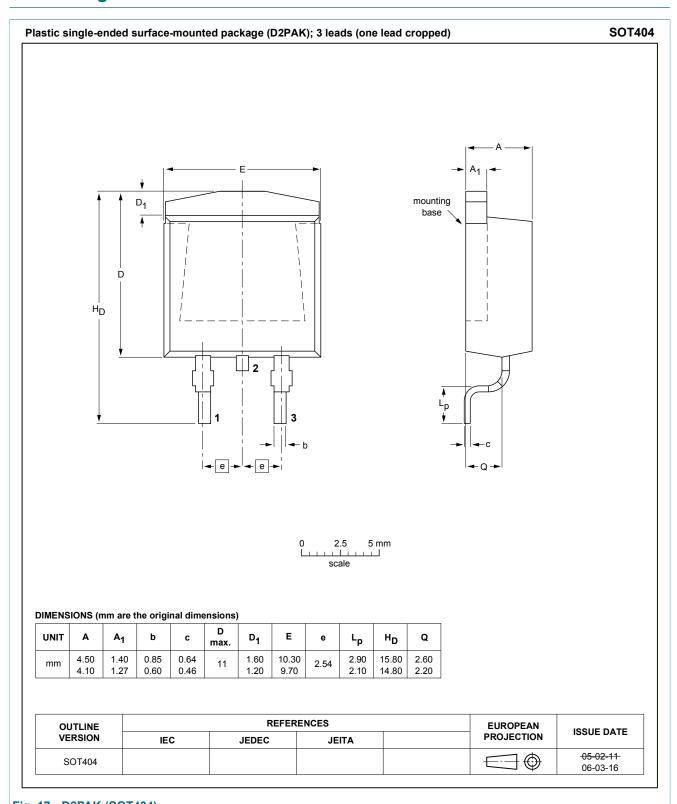


Fig. 17. D2PAK (SOT404)

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